



# PRODUCT SPECIFICATION

## (產品規格書)

### Ordering information

2211- 1\* 32 G 00 D A B

Series 1: Single No. of G: Gold Plated 00:Gold Flash D: SMD Type A: A Type B: Bulk  
Row Pin Count T: Tin Plated B: B Type Package

2211- 2\* 40 G 00 D B

Series 2: Double Row No. of G: Gold Plated 00:Gold Flash D: SMD Type B: Bulk Package  
Pin Count T: Tin Plated

L1: Dip Length

L2: Mating Length

<b>PRODUCT NAME</b> (產品名稱)	<b>DOCUMENT No.:</b> (文件編號)	<b>Rev.</b> (版本)	<b>OUPIIN</b>
PIN HEADER  1.27mm  1.27mm*2.54mm  (RoHS)	2211spec-D	A2	(歐品)
	<b>Approved</b> (核準)	<b>Checked</b> (審核)	<b>Prepared</b> (製作)
	Q.A. Section Chief	Amy Chiu	APR.18/2010



# PRODUCT SPECIFICATION OF OUPIIN

<b>1. SCOPE (範圍)</b> .....	<b>3</b>
<b>2. REFERENCE DOCUMENTS (參考文件)</b> .....	<b>3</b>
<b>3. FEATURE &amp; DIMENSIONS (特徵及尺寸)</b> .....	<b>3</b>
3.1. <i>PRODUCT DIMENSION (產品尺寸)</i> .....	3
3.2. <i>PCB/PANEL LAYOUT (印刷電路板佈局)</i> .....	3
3.3. <i>BILL OF MATERIAL (材料清單)</i> .....	3
3.4. <i>MECHANICAL &amp; ELECTRICAL CHARACTERISTIC (機械及電器特性)</i> .....	3
3.5. <i>PACKAGING (包裝)</i> .....	3
3.6. <i>STORAGE (儲存)</i> .....	4
<b>4. Environmental (環境要求)</b> .....	<b>4</b>
4.1. <i>SOLDERABILITY (可焊性)</i> .....	4
4.2. <i>RESISTANCE TO SOLDER HEAT (耐焊接熱)</i> .....	4
INFRARED REFLOW (紅外線回流焊接) .....	4
1. Preheat (預熱) .....	4
2. Soldering (焊接) .....	4
3. Cool Down (冷卻) .....	4
<b>5. PERFORMANCE AND TEST DESCRIPTION (性能及測試)</b> .....	<b>5</b>
5.1. <i>REQUIREMENT (要求)</i> .....	5
5.2. <i>TEST CONDITION (測試條件)</i> .....	5
5.3. <i>SAMPLE SELECTION (樣品選擇)</i> .....	5
<b>Table I: Test Requirements and Procedure</b> .....	<b>6-7</b>
(附錄一: 測試要求)	
<b>Table II: Reflow soldering profile</b> .....	<b>8</b>
(附錄二: 回流焊接曲線圖)	
<b>Table III: Material</b> .....	<b>9-11</b>
(附錄三: 材料證明)	

## 1. SCOPE (範圍)

This product specification defines the product performance and the test methods to ascertain the performance of the PIN HEADER 1.27mm\*2.54mm connector, which is designed and manufactured by Oupiin Electronic Co.,Ltd.

(本產品規格書規定了由歐品電子有限公司生產的 PIN HEADER 1.27mm\*2.54mm connector 型連接器,產品的特性及測試方法.)

## 2. REFERENCE DOCUMENTS (參考文件)

MIL-STD-1344A	Test method for electrical connector (電子連接器測試方法)
MIL-STD-202F	Test method for electrical components (電子零件測試方法)
EIA364	Test method for electrical components (電子零件測試方法)

## 3. FEATURE & DIMENSIONS (特徵及尺寸)

### 3.1. PRODUCT DIMENSION (產品尺寸)

These connectors shall have the dimensions as shown in drawing.

(本產品的相關尺寸參考圖面.)

### 3.2. PCB/PANEL LAYOUT (印刷電路板佈局)

The recommended PCB layout is shown in drawing.

(本產品適用的 PCB layout 參考圖面.)

### 3.3. BILL OF MATERIAL (材料清單)

Harmful material control follow the requirement of RoHS. The bill of material and product number is described in drawing.

(有害物質控制符合RoHS指令要求.本產品使用的材料參考附件.)

### 3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC (機械及電氣特性)

The connector shall have the mechanical and electrical performance as described in drawing.

(本產品的機械及電氣特性見圖面：)

### 3.5. PACKAGING (包裝)

Products shall be packaged according to requirements specified in purchase order for safe delivery.

Products required carrier tape should meet the proper specification per purchase order. Connector

container and the packaging specification is shown in package drawing.

(產品包裝可依客戶指定要求.本產品採用 Bulk Packag 包裝，具體見包裝圖面.)

### **3.6 STORAGE (儲存)**

Temperature: -40°C ~+105°C

(溫度: -40°C ~+105°C)

## **4. ENVIRONMENTAL (環境要求)**

### **4.1. SOLDERABILITY (可焊性)**

Connectors meet solder ability to MIL-STD-202F. Finish shall be free of contaminants.

(產品可焊性符合 MIL-STD-202F 標準規定的相關要求，表面不得有污染物.)

### **4.2. RESISTANCE TO SOLDER HEAT (耐焊接熱)**

#### **INFRARED REFLOW (紅外線回流焊接)**

Three cycles. Each cycle consisting of three consecutive phased.

(三個週期，每個週期包括三個連續的階段完成；)

#### **1. Preheat (預熱)**

Increase in temperature not to exceed 4°C per second.

(溫度增加不超過 4°C /秒.)

#### **2. Soldering (焊接)**

Maximum allowable time above reflow temperature of 150~200°C is 90~120 seconds. Maximum temperature in this interval is 260°C, not to exceed 5 seconds.

(回流焊溫度150~200°C時最長不超過90~120秒. 最高溫度260°C時間不超過5秒.)

#### **3. Cool Down (冷卻)**

Cool down shall not exceed 6°C per second.

(冷卻速度不超過6°C/秒.)

#### **Note: (說明)**

Device temperature measurements are referenced from the top-center of the package outer surface.

(設備溫度量測時以從頂部中間位置測量為準.)

## 5. PERFORMANCE AND TEST DESCRIPTION

### (性能及測試)

#### 5.1. REQUIREMENT (要求)

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

(本產品設計符合附表一所述的機械，電氣及環境要求。)

#### 5.2. TEST CONDITION (測試條件)

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

(除非特別注明，所有測試在室溫條件下完成；)

#### 5.3. SAMPLE SELECTION (樣品選擇)

Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.

(測試樣品從現生產的產品中隨機抽取，所有測試過的樣品不得重複使用。樣品已預先插拔10次，每組測試有5個樣品；)

## Table I: Test Requirements and Procedures

### (附錄一:測試要求)

Items (項目)	Requirements (要求)	Test Methods (檢測方法)
1. Confirmation of Product (產品確認)	Product shall be conforming to the requirements of applicable product drawing. (產品必須滿足相關檔的規定)	Check the dimensions and functions per applicable product drawing in your eyes. (目視，尺寸及功能依產品圖面檢查)
2. Contact Resistance (接觸阻抗)	20 mΩ Max. initial (最大.初態)	Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 10 mV max. (所述固定在外殼裏的端子連結到一個封閉回路中測試：電流 100 mA，電壓 10 mV max.)
3. Insulation Resistance (絕緣阻抗)	1000 MΩ Min. (最小)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC±10%). (測試產品端子間以及端子與接地間的電阻，適用：MIL-STD-202,方法 302，條件 B )(500V DC±10%)
4. Thermal shock (熱衝擊)	After testing, no damage, Contact Resistance 30 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 1000 MΩ min. (測試後,產品無損壞，接觸阻抗：30 mΩ最大；耐電壓測試 OK, 絕緣阻抗 1000MΩ最小;)	Temperature range from -40°C to +85°C .Start from -40°C, after 30 min. change to +85°C; change time is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D, condition A. (溫度變化範圍： -40°C~ +85°C；從 -40°C 開始，30 分鐘後換到+85°C；轉換時間不超過 30 秒；共 5 個循環.適用：MIL-STD-202，方法 107D，條件 A.)
5. Humidity (恆溫恆濕)	After testing, no damage, Contact Resistance 30 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 1000 MΩ min. (測試後,產品無損壞，接觸阻抗：30 mΩ最大；耐電壓測試 OK, 絕緣阻抗 1000MΩ最小;)	Temperature :85±2° C 96 hours. (溫度：85±2° C 96 小時) Relative Humidity : 90-95%; (相對濕度：90-95%；) Duration :96 Hours. MIL-STD-202, Method 108, (時間：96 小時；MIL-STD-202，方法 108。)
6.High temperature	After testing, no damage, Contact	Subject product to 85±2°C for 96 hours



## PRODUCT SPECIFICATION OF OUPIIN

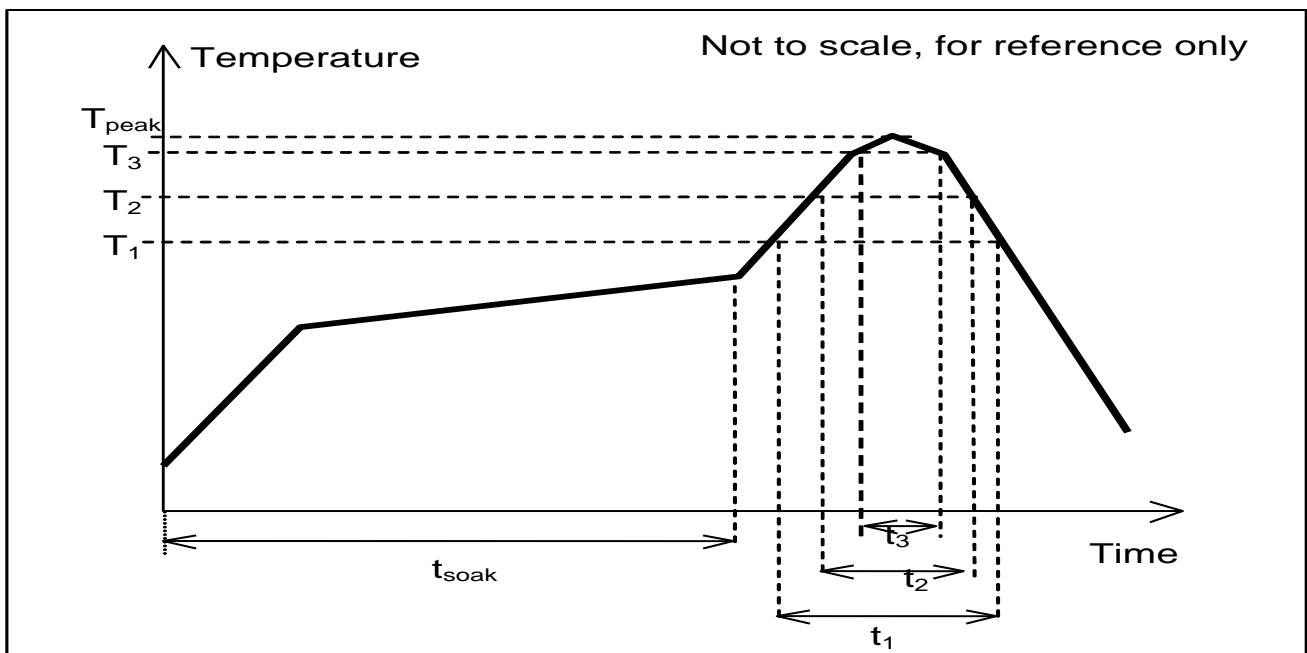
(高溫)	Resistance 30 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 1000 MΩ min. (測試後,產品無損壞,接觸阻抗: 30 mΩ 最大;耐電壓測試 OK,絕緣阻抗 1000MΩ 最小;)	continuously. MIL-STD-202, Method 108. (產品置於 85±2°C 連續 96 小時,適用 MIL-STD-202,方法 108。)
7. Solder ability (可焊性)	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10 X for any damage such as pinholes, void or rough surface. (樣品在測試完成後,在放大倍數為 10 倍的顯微鏡下,檢查外觀損壞如:小孔,空焊,外觀粗糙度;)	Soldering time: 3 to 5 Seconds (焊接時間: 3~5 秒) Peak Temperature: 245±5°C. (最高溫度: 245±5°C.)
8. Resistance to soldering heat 耐焊接熱	No damage 產品無損壞	Leave subject product in the 260±5°C chamber for 5 Seconds 產品置於 260±5°C 烘箱內 5 秒。

**Table II: Reflow soldering profile**

(附錄二:回流焊接曲線圖)

**Pb-free reflow profile requirements: (無鉛回流焊接曲線)**

Parameter (參數)	Reference (參考)	Specification (規格)
Average Temperature Gradient in Preheating (平均預熱溫度)		2.5°C/s
Soak Time 25~150°C	$T_{soak}$	60 Seconds (max)
Time Above 150~200°C	$t_1$	120 Seconds (max)
Time Above 200~230°C	$t_2$	50 Seconds (max)
Time Above 230~255°C	$t_3$	5 Seconds (max)
Peak temperature in reflow (回流焊接中最高溫度)	$T_{peak}$	260°C (-0/+5°C)
Temperature Gradient in Cooling (冷卻時溫度幅度)		Max -5°C/s



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

(這個曲線圖是評估原器件焊接抗熱的基本要求。應用在對流焊接中的熱傳遞方式是熱氣對流。達到特定曲線圖的實際溫度主要依賴於回流焊接設備。)





# PRODUCT SPECIFICATION OF OUPIIN

Material Housing : 041-PA9T

[SGS Test Report Click here](#)

[如需 SGS 測試報告請點選此處](#)

## Material properties of Genestar

Grade	Unit	Test method	Genestar (flame-retardant grade)										Other products for reference				
			G2330	G2330	GR2300	GN2330	GN2450	GT2330	GN2332	GW2458HF	GW2508	PA6T	PA46	PPS	LCP	LCP	
Type		(ASTM)	9	12	1	1	1	2	1	1	1	1	Zytel	Stanyl	Fortron	Zenite	Vectora
			standard	standard	high weld strength	high weld strength	high weld strength	toughness	high flow	low warpage, high flow	low warpage, high strength		FR52G30I	TE250F8	1140A6	6130L	E130I
Glass fiber content	%	-	33	33	30	33	45	33	33	45	50		30	40	40	30	30
<b>Physical properties</b>																	
Specific gravity	g/cm3	-	1.68	1.68	1.57	1.62	1.73	1.58	1.62	1.73	1.78		1.65	1.68	1.67	1.62	1.61
Water absorption (105F/40C/95%RH/96hrs)	%	-	0.9	0.9	1.1	1.0	0.7	1.0	1.0	0.8	0.7		2.6	3.6	0.06	[0.04]	[0.04]
Flammability	-	UL94	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0		V-0	V-0	V-0	V-0	V-0
<b>Mechanical properties</b>																	
Tensile strength	MPa	D638	175	185	184	190	210	195	172	175	185		179	163	208	150	150
Tensile elongation	%	D638	2.8	3.1	2.7	3.2	2.6	3.2	2.6	2.5	2.5		2.7	2.8	2.5	2.7	2.4
Weld strength	MPa	D638	45	45	51	54	40	60	36	35	35		57	57	67	22	20
Weld elongation	%	D638	0.5	0.5	0.7	0.7	0.4	0.8	0.3	0.3	0.3		0.7	0.7	0.7	0.2	0.2
Flexural strength	MPa	D790	222	222	209	225	260	233	210	222	245		227	223	257	170	167
Flexural modulus	GPa	D790	11	11	9	11	14	10	10	15	16		10	12	13	12	11
Izod impact strength (notched)	J/m	D256	100	100	100	100	100	100	100	100	100		90	90	80	120	116
Bar-flow length (610F/320C/0.5mm/750kgf)	mm	-	67	66	63	55	37	45	85	71	50		60	82 (590F)	31	85 (645F)	80 (645F)
Rockwell hardness	R scale	D785	125	125	125	125	125	125	125	125	125		125	125	123	-	-
<b>Thermal properties</b>																	
Melting point	F/C	-	583/306	583/306	583/306	583/306	583/306	583/306	583/306	583/306	583/306		590/310	563/295	536/280	-	-
Glass transition	F/C	-	257/125	257/125	257/125	257/125	257/125	257/125	257/125	257/125	257/125		185/85	140/60	194/90	-	-
DTUL (1.82MPa)	F/C	D648	545/285	545/285	545/285	545/285	545/285	545/285	545/285	545/285	545/285		545/285	545/285	509/265	509/265	527/275
<b>Electrical properties</b>																	
Dielectric strength	MV/m	D149	30	30	30	30	30	30	30	30	30		[28]	24	24	[30]	[30]
Volume resistivity	Ωcm	D257	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>	10 <sup>15</sup>		[10 <sup>15</sup> ]	10 <sup>15</sup>	10 <sup>15</sup>	[10 <sup>16</sup> ]	[10 <sup>16</sup> ]
Tracking resistance	V	IEC-CTI	550	550		400	400	400	400	>600	400		[400]	225	175	[175]	[175]
Dielectric constant (10GHz)	-	D150	3.7	3.4		3.4	[3.8]	[3.4]	3.5	3.8	3.9		[3.4]	4.1	3.8	[4.2]	[4.2]
Dielectric loss tangent (10GHz)	-	D150	0.012	0.0095		0.0097	[0.0097]	[0.0097]	0.0101	0.0098	0.0098		[0.009]	0.0123	0.0064	[0.018]	[0.018]
<b>Dimensional characteristics</b>																	
Molding shrinkage in direction of flow (1mm)	%	-	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.03	0.02		0.1	0.1	0.04	0.1	0.1
at right angles to flow	%	-	0.6	0.6	0.6	0.6	0.5	0.6	0.6	0.40	0.30		0.6	0.7	0.50	0.6	0.6

\* Table shows typical values, which are not specified values.



# PRODUCT SPECIFICATION OF OUPIIN

## Material Housing :UL



QMFZ2 Component - Plastics

Wednesday, August 25, 2004

E90350

KURARAY CO LTD

HIGH PERFORMANCE MATERIALS DEV DEPT 1-12-39 UMEDA KITA-KU OSAKA 530-0001 JAPAN

Material Designation: **GW2458HF**

Product Description: Polyamide 9T (PA9T), furnished as pellets.

Color	Min. Thick. (mm)	Flame Class	HWI	HAI	RTI Elec	RTI Imp	RTI Str	IEC GWIT	IEC GWFI
ALL	0.75	V-0	0	0	150	130	140	-	-
	1.5	V-0	0	0	150	130	140	-	-
	3.0	V-0	0	0	150	130	140	-	-

**CTI: 0**

**HVTR: 4**

**D495: 5**

IEC Ball Pressure (°C): -

Dielectric Strength (kV/mm): -

Volume Resistivity (10<sup>9</sup>ohm-cm): -

Dimensional Stability(%): -

ISO Tensile Strength (MPa): -

ISO Flexural Strength (MPa): -

ISO Heat Deflection (°C): -

ISO Tensile Impact (kJ/m<sup>2</sup>): -

ISO Izod Impact (kJ/m<sup>2</sup>): -

ISO Charpy Impact (kJ/m<sup>2</sup>): -

Report Date: 7/10/2002

Underwriters Laboratories Inc®

UL94 small-scale test data does not pertain to building materials, furnishings and related contents. UL 94 small-scale test data

is intended solely for determining the flammability of plastic materials used in components and parts of end-product devices

and appliances, where the acceptability of the combination is determined by ULI.



# PRODUCT SPECIFICATION OF OUPIIN

Material Contact :Copper Alloy (SQUAREPIN-Au)

[SGS Test Report Click Here](#)

[如需 SGS 測試報告請點選此處](#)

國 晟 工 業 股 份 有 限 公 司

GWO CHERN INDUSTRIAL CO., LTD.

桃園縣蘆竹鄉海湖村海湖 16 鄰 186 之 28 號

No . 186 – 28 Hai Hu Village . Lu Chu

Hsiang Tao Yuan Hsien Taiwan

## 電腦分析儀化學成份(CHEMICAL COMPOSITIONS)測試報告

客戶名稱						
訂單號碼				出貨日期	96/10/24	
國際標準	JIS 國際標準	試材品名	C2700W (SBS)	試材規格	1.08m/m ± 0.02	
化學試驗	CHEMICAL TESTING					
儀器名稱	X 光電腦分析儀 (VACUUM X RAY SPECTROGRAPH)					
此份材質表僅供參考，不做其他證明使用。						
元素名稱	標準規範 %	實際含量 %	元素名稱	標準規範 %	實際含量 %	
銅 (Cu)	63.2-63.8	63.485	鐵 (Fe)	≤ 0.02	0.0017	
鋅 (Zn)	Remainder	36.4794	矽 (Si)	—	—	
鉛 (Pb)	≤ 0.010	≤ 0.01	錳 (Mn)	—	—	
錫 (Sn)	Fe+Sn ≤ 0.02	≤ 0.02	銻 (Sb)	—	—	
鎳 (Ni)	—	—	鋁 (Al)	≤ 0.005	0.0039	
磷 (P)	—	—	其他(other)	—	—	
導電率測試值	架橋式					
機械試驗	MECHANICAL TESTING					
試驗方法	油壓拉伸法					
儀器名稱	電腦萬能材料試驗機 ( computer universal machine)					
物理性質	拉力(tesile strength)	降伏點(yield strength)	延伸率(elongation)	硬度(hardness)	CD 值 1	CP 值 2
標準要求	— kgf/m <sup>2</sup>	— gf/m <sup>2</sup>	15 % 以上	1/4 H	750 m/m 以下	50 m/m 以下
實際數值	36.9 kgf/m <sup>2</sup>	18.12 kgf/m <sup>2</sup>	37 %	1/4 H	550 m/m	<5 m/m
製造批號	101821	101822				
單位主管	張 景 松		分 析 員	何 三 吾		